



IEEE MTT-S Latin America Microwave Conference (LAMC-2025) - January 22-24, 2025 - San Juan, Puerto Rico

LAMC 2025 Call for Papers

General Chair:

Rafael A. Rodríguez Solís, UPRM, Puerto Rico. rarsolis@ieee.org

General Co-Chair: Leyda León Colón, UPRM, Puerto Rico. leyda.leon@upr.edu

Technical Program Chair: Roberto S. Murphy, INAOE, Mexico. rmurphy@ieee.org

Technical Program Co-Chair: Héctor J. De Los Santos, Ph.D. NanoMEMS Research, LLC. ask@nanomems-research.com

Financial Chair: Rafael H. Medina Sánchez, UPRM, Puerto Rico. rafael.medina1@upr.edu

MLVC Chair: Eduardo A. Rojas-Nastrucci, ERAU, Florida, USA. rojase1@erau.edu

YP/Student Coordinator: Valeria González, CINVESTAV, Mexico. Valy.mx@ieee.org

WiE Coordinator:

Edna Moreno-Mojica, Synopsys, Mexico. ednamoreno@ieee.org

Publicity & Public Relations Chair: José Rayas-Sanchez, ITESO, Mexico. erayas@iteso.mx

Webmaster:

Zulmarian Castro, Digital Media and PR Services, LLC, Puerto Rico. digitalmediapr2@gmail.com



The fifth edition of **LAMC will take place in San Juan, Puerto Rico, on January 22-24, 2025.** After four successful editions in Puerto Vallarta, Mexico (2016), Arequipa, Peru (2018), Cali, Colombia (2021, virtual), and San José, Costa Rica (2023), LAMC goes to San Juan as a high-quality technical forum for the Latin America region and all the MTT-S community. San Juan, located on the north coast of Puerto Rico, is rich in culture, tradition, and history, being one of the most important settlements in the Caribbean since the early 1500's. It is conveniently served by airlines from many countries, which have frequent flights to Luis Munoz Marin International Airport (SJU). LAMC-2025 will be co-located with RWW-2025.

We encourage the submission of original, unpublished research focused on (but not limited to) the following topics of interest:

- 1. **Passive components, circuits, and devices** (planar and nonplanar components and circuits, filters and multiplexers, tunable devices, and metamaterials).
- 2. Active devices, circuits, and measurement systems (RFICs & MMIC design, power amplifiers, linearization techniques, low-noise circuits, signal generation, conversion & control modules, linear and non-linear modeling, and measurement techniques).
- 3. **RF systems and applications** (microwave systems and front-ends industrial scientific and medical applications, navigation systems, intelligent transportation systems, imaging, sensors, wireless power transmission).
- 4. **Communication systems** (terrestrial, vehicular, satellite and indoor applications, wireless and cellular communication systems).

- 5. Active and passive antennas (phase arrays, integrated antennas, smart antennas, digital beam forming and MIMO).
- 6. Signal-power integrity and high-speed digital techniques (EM interference and compatibility, high-speed interconnects, post-silicon validation techniques, power delivery networks, computer simulations and measurements).
- 7. CAD techniques for RF and microwave engineering (surrogate-based modeling and optimization, space mapping-based methods, model order reduction, machine learning approaches, statistical analysis and design, EM-based and multi-physics design optimization, EM field theory, time- and frequency-domain numerical techniques).

Papers submitted to LAMC 2025 will be peer reviewed and evaluated based on originality, quantitative content, clarity, and interest to the audience. The review process will be single-blind. LAMC will use EDAS as the electronic paper management system. All accepted and presented papers will be published in the LAMC Conference Proceedings and submitted for inclusion in the *IEEE Xplore Digital Library*.

English will be the official language of the conference. Prospective authors are cordially invited to submit a three-page two-column manuscript, following the instructions available at the conference website, (https://lamc-ieee.org).

Important Dates:

Proposals for special sessions and tutorials: Submission regular papers: Notification of acceptance: Camera-ready submission: Author registration deadline: July 29, 2024 August 26, 2024 September 30, 2024 October 14, 2024 October 15, 2024 July 29, 2024 September 9, 2024 October 7, 2024 October 18, 2024 October 25, 2024



